

Solutions for Research,

Development & Production



ADVANCED MATERIALS

Leading supplier of advanced materials for research, industrial, and laboratory applications. These include:

- Metal Single Crystals
 & Bicrystals
- Highest Purity Materials
- Oxide Single Crystals
- Evaporation Materials
- Thin Film Materials
 - Sputtering Targets
 - Backing Plates
 - Bonding

- Optical Materials
 - · Fluorides (BaF2, CaF2, LiF, MgF2)
 - · Chlorides (AgCl, NaCl, KCl, KBr)
 - Infrared (ZnSe, ZnS, Ge, Si)
 - Monocrystalline: Sapphire, Quartz
 - · Undoped Garnets: YAG, GGG
- III-V Materials
- Re-polishing & orienting of customer's samples



PRECISION WIRE SAWS

- Can cut semiconductors, ferrites, metals, glasses and other hard or brittle solids. Cut samples using two different methods (wet and dry cut)
- Cut surfaces of nearly "lapped" quality
- Minimal loss of material
- Cutting that does not introduce deformations
- Wire diameters from 20µm to 60µm
- No "wandering" of cutting wire in an unintended direction
- Cut under any desired angle feasible
- Cut samples up to a size of 80x80x150mm
- Semi-automatic, requires no supervision



NLO/LASER CRYSTALS

- KTO
- KTA
- KDP
- BB0
- LiNb03
- LiTaO3
- Cr:YAG
- Mg0:LiNb03
- YAG Crystals: Er:YAG, Nd:YAG, Yb:YAG, Cr, Tm, Ho:YAG
- YLF Crystals: Ho:YLF, Nd:YLF, Tm:YLF, Er:YLF
- ➤ YSGG Crystals: Er: YSGG, Er, Cr:YSGG, Cr, Nd:YSGG
- YAP Crystals: Er:YAP, Nd:YAP, Tm:YAP
- Other:
 Alexandrite,
 Ti:Sapphire,
 Forsterite,
 Nd:YV04, Diffusion bonded crystals



PARTICLE BEAM LINE

We supply products and services to the accelerator scientific community.

- Vacuum Technology
- Particle Accelerators
- Beam Diagnostics
- High Vacuum Feedthroughs
- Metal-Ceramic Bonds
- Beam Stopper
- RFQ Accelerator Structures
- Variable Segmented Aperture
- Jaw Slit Systems
- Rotating Wire Scanner

About Princeton Scientific Corporation

Founded in 1991, Princeton Scientific Corp. is a worldwide supplier of material science & engineering related products, plus particle beam technology, precision wire saws, UHV technology and plasma technology for scientists, engineers and industrial manufacturers.



MATERIALS



PRECISION WIRE SAWS



PARTICLE BEAM LINE



UHV TECHNOLOGY



ADDITIONAL SERVICES

We have an excellent and long-standing reputation for Metallic Single Crystals,
Sputtering Targets, Superconductor substrates,
Laser Crystals, Optical Materials, Opto-Electronic
Components, and various Oxide Crystalline
Materials within the scientific community.

Not only do we offer crystal boules, blanks, semifinished and finished products in the form of wafers, windows, lenses, prisms, tubes, rods, and crucibles but also cutting and polishing services for such materials.

In addition to materials, we also offer Precision Wire Saws, Diamond Wire Saws, Particle Beam Line & Diagnostics, UHV Technology, Plasma Systems.

Princeton Scientific Corp. now offers:

- Diamond Wire Saws
- Particle Beam Line & Diagnostics
- Plasma Systems
- UHV Instruments/Components

All of these devices are designed and built to the highest quality standards.



Sputtering Targets



Princeton Scientific Corp. offers sputtering targets made of metals, non-metals and chemical compounds with purities ranging from 99.9% to 99.9999%.

We offer standard, single element, pure metals and custom compounds. We also have various geometric shapes. Round, rectangular, as well as multi-tile and stepped constructions are possible.

Please review our standard and specialty target list for more information. Princeton Scientific can produce sputtering targets to your specific needs. We will help to select appropriate target material, fabrication process, and bonding assembly that ensures the success of your thin deposition process. Our sputter targets are prepared either by a melt or powder metallurgical process.

We also provide an array of backing plates for your system's requirements, and our bonding services include various metallic or silver epoxy techniques.

BORIDES	CARBIDES	FLUORIDES	NITRIDES	SILICIDES
CrB2	B4C	AIF3	AIN	CrSi2
HfB2	Cr3C2	BaF2	BN	Cr3Si
LaB6	HfC	CaF2	HfN	HfSi2
Mo2B6	Mo2C	CeF3	NbN	MoSi2
NbB2	NbC	LaF3	Si3N4	NbSi2
TaB2	SiC	PbF2	TaN	PtSi
TiB2	TaC	LiF	TiN	TaSi2
WB	TiC	MgF2	VN	Ta5Si3
W2B	WC	KF	ZrN	TiSi2
VB2	WC 6%Co	Re/NaF	and others	Ti5Si3
ZrB2	WC 12%Co	Na3AlF6		WSi2
and others	VC	ThF4		VSi2
	ZrC	YF3		V3Si
	and others	and others		ZrSi2
				and others

SULFIDES, SELENIDES, TELLURIDES						
As2S3	PbS	NbSe2	TaTe2	ZnS		
CdSe	PbTe	Nb-S	WSe2	ZnTe		
CdS	MoSe2	NbTe2	WS2	and others		
CdTe	MoS2	TaSe2	WTe2			
PbSe	MoTe2	TaS2	ZnSe			

		METALS	1/	
Aluminium	Chromium	Lead	Platinum	Tantalum
Antimony	Cobalt	Lithium	Potassium	Tellurium
Barium	Gallium	Magnesium	Rhenium	Tin
Beryllium	Germanium	Manganese	Rhodium	Titanium
Bismuth	Gold	Molybdenum	Rubidium	Tungsten
Boron	Hafnium	Niobium	Ruthenium	Vanadium
Cadmium	Indium	Nickel	Selenium	Zinc
Calcium	Iridium	Osmium	Silicon	Zirconium
	Iron	Palladium	Strontium	
1		RARE EARTH		T.A-1/
Cerium	Gadolinium	Neodymium	Terbium	Various Rare
Dysprosium	Holmium	Praseodymium	Thulium	Earth Alloys
Erbium	Lutetium	Samarium	Ytterbium	
Europium	Lanthanum	Scandium	Yttrium	
		ALLOYS		7/7/2
AI/B	Au/Pd	Co/Ni	Ge/Si	Pt/Ru
AI/Cu	Au/Pt	Co/Ta/Zr	Ge/Te	Pt/Ag
AI/Cu/Si	Au/Sn	Cr/SiO2 Cermet	In/Sn	Sb/In
AI/Cr	Au/Zn	Cu/Al	Ir/Mn	Sb/In/Sn
AI/Li	Bi/Sb	Cu/Cr	Ni/Cr	Si/AI
AI/Mg	Bi/Sb /Se	Cu/Ga	Ni/Fe	Si/Cr
AI/Si	Bi/Sb/Se/Te	Cu/Ni	Ni/Ti	Ta/Ti
AI/Ti	Bi/Sb /Te	Cu/Sn	Ni/V	Ti/AI
Au/Sb	Bi/Se	Fe/AI/Si	Ni/Zr	Ti/W
Au/Ag	Bi/Te	Fe/Cr	Os/Ru	Ti/Zr
Au/B	Cd/Te	Fe/Mn	Pb/Se	W/Ti
Au/Be	Co/Cr	Fe/Ru/Ga/Si	Pb/Te	Zn/Al
Au/Ge	Co/Fe	Fe/Si	Pb/Se/Te	Zr/Y
Au/Ir	Co/Nb/Zr	PFe/Si/B/C	Pd/Pt	And others
A = 0		OXIDES	17	
Al203	CuO	PbZrO3	Supercond.	Y203
Sb203	Hf02 unstab.	LiNb03	SrO	Zn0
BaTiO3	Hf02/Ca0	Mg0	SrTi03	ZnO dop.
Bi203	Hf02/Y203	Mo03	SrZr03	ZrO2 unstab.
Bi2Ti05	In203	Nb203	Ta205	ZrO2/CaO
Bi4Ti3O12	ITO	Nb205	ThO2	Zr02/Y203
BiTiO3	LaAl03	Re203	Sn02	and others
CeO2	La203	SiO2	TiO2	
Cr03	PbTiO3	SiO	W03	

Backing Plates

Backing plates are available in the following materials:

- ► Copper
- ► Stainless Steel
- ► Aluminum
- Molybdenum
- ► Invar
- ▶ Kovar



Metal Crystals



Application: Metal single crystals are required, among others, for basic research (surface physics, catalytic chemistry, investigation of material properties), for monochromators (X-ray, neutrons) and electrons (W-needles, LaB6, CeB6).

Properties: The quality of our crystals is characterized by an especially high mosaicity.

Production of metallic single crystals is carried out in most modern equipment with highest quality requirements. For crystal growth using the Bridgman-, Czochralski- and zone melting techniques only highest purity starting materials are used.

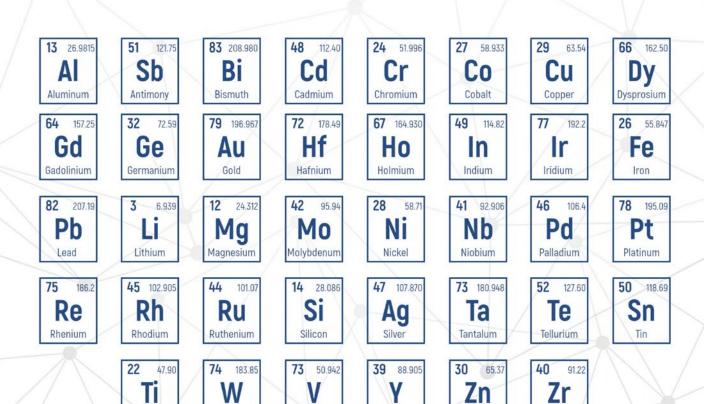
Titanium

Mosaicity of the elements: the mosaicity describes the deviation of the perfect structure of the crystal. It is the angle specification which describes the deviation of a reflective X-ray jet and the ideal reflex angle. A small angle stands for a perfect crystal structure.

During application of the surface, particular emphasis will be put on orientation accuracy of the crystallographic direction. **Orientation accuracy**: up to <0.05°.

The especially careful surface conditioning (polishing) allows, after low heat and sputter cycles, the direct investigation of up to several 1000 nm spread nuclear terraces. **Polishing:** roughness < 1nm (also with soft elements like Au or Pb).

Geometric: Several geometries are available. See our website for all geometries we offer. When requesting a quote, please specify geometric shape. In case the desired geometrics are no available on our website, please send us a drawing for a quote.



Vanadium

Tungsten

Yttrium

Zinc

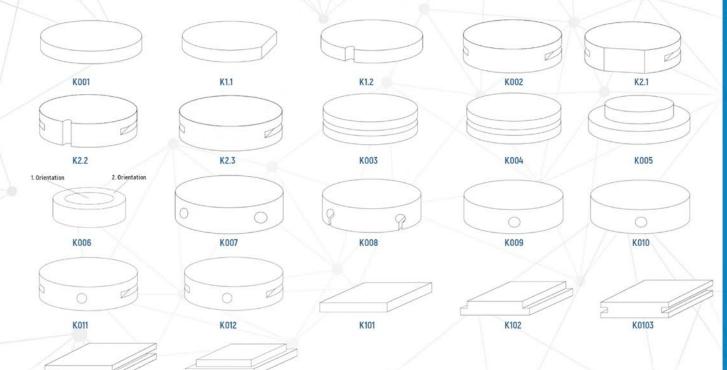
Zirconium

Metal Crystals



Available Geometries

Princeton Scientific offers various geometric shapes when it comes to Metal Single Crystals. Below you will find the most common shapes, however custom designs are also feasible. Detailed drawings with template specifications required for quotation are listed on our website at www.princetonscientific.com/materials/metal-single-crystal-geometries/.



 High-Quality Crystal Processing of customer provided materials

K104

- Re-polishing of customer provided materials (both or single side)
 - Roughness <10nm (typically 1nm for hard metals and typically <1-5nm for soft metals, even for Pb)

K105

- ▷ orientation accuracy <2 deg</p>
- → orientation accuracy < 0.4°
 </p>
- □ orientation accuracy <0.1°
 □ [possible up to <0.05°]
 </p>

Additional Services



- Cutting and/or orienting customer provided crystals
- Laue pictures
- Measuring of roughness
- Diverse cuttings and cut of geometrics according to your specifications
- Diverse drillings
- Etching of the surface according to your specifications
- Install of a wire for direct electronic contact of the sample
- Bonding & de-bonding of sputtering targets
- Complete coating services



Evaporation Materials



Princeton Scientific Corp. provides a wide variety of evaporation materials for the vacuum deposition industry. Our materials are available in various purities ranging from 99.9% to 99.99999%. Evaporation material can be made to order in the following forms:

- ► Chunk
- ► Foil
- Pellet
- ► Wire
- Rod
- ► Shot
- ► Slug
- ► Starter
- ➤ Source
- ► Tablet
- ▶ Granules
- Pieces

			EVAPORATION MATE	RIALS		
Al	CaF2	Eu	La203	Ni2B	Na2CO3	TiSi2
AISb	CaH2	Eu203	(La0.7Sr0.3)Mn03	NiSi2	NaCl	W
AIB2	CaO	Gd	LaTiO3	NiO	NaF	WC
AIF3	CaS	Gd2F3	Pb	NiTe	Na202	W03
Al203	CaTiO3	Gd3Ga5012	PbO	Nb	Sr	WaSe2
AIP	Ca3(P04)2	Ga	PbTe	NbC	SrC03	WSi2
Sb	Ca10 (OH)2 (PO4)6	GaSb	Li	Nb205	SrF2	WS2
Sb2S3	С	GaAs	Li2CO3	Nb02	SrMo04	WTe2
Sb203	Ce	GaŅ	Li2CO3	NbSe2	Sr0	V
Sb2Te3	CeB6	Ga203	LiF	Os	SrRu03	VC
As	CeF3	Ge	LiMn204	Pd	SrS	V02
As203	CeO2	Ge3N4	LiNb03	PdO	SrTi03	VN
As2Te3	CsF	GeO2	Li20	P	SrZr03	V203
BST	Csl	GeSe2	Li3PO4	P205	S	V205
BaS	Cr	GeS	Lu	Pt	Ta	VSe2
BaZrO3	Cr03	GeTe	Lu203	KNb03	TaC	V2S3
Ba	CrB2	Au	Mg	Pr	TaN	Yb
BaFe12019	Cr3C2	Hf	MgAl204	Pr203	Ta205	YbF3
BaF2	CrF3	HfC	MgB2	Re	TaSe2	Yb203
Ba0	Cr2N	Hf02	MgF2	Rh	TaSi2	Y
Ba02	Cr203	Но	MgO	Rh203	Te	Y3AI5012
BaTiO(3)	CrSi2	Ho203	Mg2Si	Ru	TeO2	Y3Fe5012
Bi	Cr2S3	In	MgS	Ru02	Tb	YF3
Bi203	Co	In2Te3	Mn	Sm	TbF3	Y203
Bi2S3	CoFe204	InSb	Mn0	SmF3	TbOF	Zn
Bi2Te3	CoO	InN	Mn02	Sm203	Tb407	ZnF2
Bi4Ti3012	Co304	In203	Mn203	Sc	Sn	Zn3N2
В	CoSi2	In203/Sn02	MnTe	Sc203	SnF2	ZnO
B4C	Cu	lr/	НдТе	Se	Sn02	Zn3P2
BN	CuS	IrO2	Mo	SeO2	SnS2	ZnSe
B203	Cu20	Fe	MoB	Si	SnTe	ZnS
Cd	CuO	FeB	Mo2C	SiC	Ti /	ZnTe
Cd3As2	Cu3P	Fe3C	MoS2	SiO2	Ti3Al	Zr
CdCl2	CuSe	NiFe204	MoO3	Si0	TjB2	ZrB2
CdF2	Cu2S	Fe203	MoO2	Si3N4	TiC	ZrC
Cd0	Dy	Fe304	MoSe2	SiS2	Ti02	ZrCl4
CdSe	DyF3	FeSi2	MoSi2	Ag	TiF3	ZrF4
Cd2Sn04	Dy203	FeS2	MoTe2	AgCI	TiO	ZrN
CdS	Er	La	Nd	Ag20	TiN	Zr02
CdTe	ErF3	LaAl03	Nd203	Na	Ti203	ZrSi2
Ca	Er203	LaB6	Ni	Na5Al3F14	TiSe2	Zr02/Y203
Ca	Er203	LaB6	Ni	Na5Al3F14	TiSe2	

Laser Crystals





We offer common host crystals such as YAG (Yttrium Aluminum Garnet) or YVO4 (Yttrium Orthovanadate) with various dopants such as Neodymium, Ytterbium, Erbium and Chromium. The ready to use coated or uncoated laser rods are manufactured to the highest standards of our crystal technology. All of the LASER COMPONENTS' AR coatings are optimized for high power lasers and are available for the wavelength range from 193 nm to 3000 nm.

Both the bandwidth (depending on the wavelength) and the effectiveness of the coating can be influenced by the various designs, and different coating materials. Thus the optimal coating for each application can be made available. Custom sizes, polished, unpolished, coated, and uncoated crystals are available upon request. Please provide us with your detailed specs or drawing so we can provide our most competitive offer.

NLO CRYSTALS

LBO BBO KTP GTR-KTP RTP KTA



KTA Bi8306 LiNb03 Mg0:LiNb03 KD*P & KDP Lil03

Nd:YLF

LASER CRYSTALS

Nd:YV04 Nd:GdV04 Nd:YAG Cr4+:YAG Ho:Cr:Tm:YAG Nd:Ce:YAG Yb:YAG Er:YAG Ce:YAG Ti:Sapphire Nd:GGG



Tm:YLF
Ho:YLF
Nd:KGW
Yb:KGW
Er:YAP
Nd:YAP
Forsterite
Alexandrite
Er:Cr:YSGG
Diffusion Bonded Crystals

ACOUSTO-OPTIC CRYSTALS AND ELECTRO-OPTIC CRYSTALS

LiNb03

BIREFRINGENT CRYSTALS

YV04 a-BB0 LiNb03

SCINTILLATION CRYSTALS

Csl LaBr3(Ce) YAG (Ce)

Nal (TI) LaCl3(Ce)

MAGNETO-OPTICAL CRYSTALS

TGG

TSAG



Dropometers



Smart measurement instrument with an automatic dropper for surface energy research.



COST-EFFECTIVE

Our instrument drastically reduces the initial investment costs associated with tensiometers while maintaining high end features.



EASY TO USE

The app at the heart of the Dropometer is simple and intuitive to use, bypassing any need for paid user-training courses. With our Dropometer you can be up and running in less than twenty minutes.



SMARTPHONE-BASED

The system doesn't require the use of additional laptops or desktop computers and benefits from the full connectivity of a smartphone.



MEASUREMENT

Static and dynamic contact angle Static and dynamic surface tension Sliding angle Surface energy

METHODS

Young-Laplace and Polynomial
Young-Laplace
Polynomial
Equation of States, Fowkes, Oss and Good

oducts specificat	ions Sessile	Energy	Tilted	Pendant
EASUREMENT				
ange	10° to 175°	Up to 100 mN/m	10° to 175°	Up to 75 mN/m
esolution	0.01°	0.01 mN/m	0.01°	0.01 mN/m
ccuracy	0.35°	0.03 mN/m	0.35°	0.03 mN/m
odel	Young-Laplace Ec	quation of states, Fowkes and, Oss and Good	Polynomial	Young-Laplace
rop type So	essile advancing, receding and static	Sessile static	Tilting sessile	Pendant static and dynamic
TING PLATE AND I	DOSING			
ontrol		M	lanual and Automatic	
ange		0	° to 60°	
osing system		M	lanual & Automatic	
inimum Drop Volun	ne with Automatic Dosing	0	.05 μL	
rop Volume with Ma	anual Dropper	1	rotation is 5.29 μL	
OFTWARE				
pplication		A	ndroid and iOS based	software
ecurity		M	lultiple user account	per device
ata sharing		E	mail and cloud (Goog	le drive, Dropbox, MS One drive an
terfaces		В	luetooth, wifi, usb, ce	llular
AMERA				
erformace		1) fps	
oom		Z	oom	
ocus		4	<u> </u>	
ocus		/ / N	lanual	
ensor			rigger control based	on camera level
LUMINATION				
/pe		Н	igh power LED	
ze			8 by 51 mm	
NVIRONMENT				
emperature		1)° to 45°	
umidity		V	/ithout condensation	
STRUMENT DIMEI	NSION			
ootprint		3	O(H) x 15(W) x 45(L) cr	m /
eight			kg	
OWER				
			V battery only operat	tion*
oltage		n	v pattery timy nuerai	HUII / N



Princeton Scientific Corp. supplies products and services to the accelerator scientific community. Our areas of expertise include beamline systems, and beam diagnostic devices for research-, industrial-, and commercial accelerator systems.

We specialize in designing accelerator-related equipment. Our many industry contacts - such as scientists & engineers all over the world - support commitment to innovation, quality, and customer satisfaction. We provide end to end design and engineering and integration solutions to scientists worldwide. Our Faraday Cups, Beam Stoppers, Beam Profile Measurement Systems and UHV Linear and Rotating Feedthroughs are well known within the scientific community.

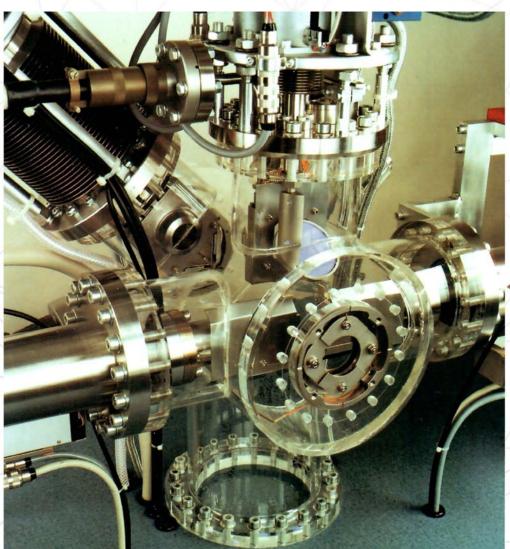
- Vaccum Chambers
- High Vacuum Feedthroughs
- Metal-Ceramic Bonds
- Beam Profile Measuring System
- **Emittance Measurement Device**
- Beam Stopper

- Faraday Cups
- **RFQ Accelerator Structures**
- Variable Segmented Aperture
- Capacitive Pick-Up Probes
- Jaw Slit Systems
- Rotating Wire Scanner











Particle Beam Line

VACUUM TECHNOLOGY

We design and manufacture vacuum chambers of different shapes for various applications. As a speciality, we offer Al-chambers with inhouse developed Bi-metal-flanges.



BEAM DIAGNOSTICS

We provide an extensive range of solutions, where customization is our standard practice

- ► Faraday Cups
- ► Beam Profile Monitors
- ► Capacitive Pick-Up Probes
- ► Emittance Scanners



PARTICLE ACCELERATORS

We have extensive experience in the field of particle accelerator design and manufacturing.

- ► IH-structures
- ► CH-structures
- ► Special Resonators, e.g. Buncher Cavities



RFQ ACCELERATOR STRUCTURES

Various RFQ structures of the 4-rod type.

- ► Design and manufacturing of RF-systems
- ► Design and manufacturing of vacuum systems
- ► Delivery of a control system via PC or VME

BEAM STOPPER

The beam stopper is provided to collect accelerated particles and can be mounted on the end of a beam line or on the down-stream flange of a standard diagnostics chamber.



VARIABLE SEGMENTED APERTURE

The variable segmented aperture fits into the entrance ports of vacuum chambers for e.g. beam size limitation or rough estimation of beam position.



HIGH VACUUM FEEDTHROUGHS

Universal precision high vacuum feedthrough with an accuracy of positioning of +0.03mm (single or twin version)

JAW SLIT SYSTEMS

Jaw slit systems available (with UHV-Feedthrough, Type LM 17) are used for beam size limitation, beam analysis functions, and energy definition in beam transport systems of particle accelerators.

METAL-CERAMIC BONDS

Ceramic chambers are widely used in accelerator units for injection, fast extraction and beam excitation.



ROTATING WIRE SCANNER

For measurement of beam intensity profiles versus transverse coordinates.





UHV Technology

MANIPULATORS, DRIVES & MOTIONS

- Manipulators
 - Single Bellows
- Dual Bellows
- Sample Holders
- Sample Heating
- Motor Controllers
- XY Modules
- Drives and Motions
- UHV Linear Drives
- Rotary Drives
- Wobble Sticks
- Magnetic Transfer Probes
- Non-magnetic Transfer Probes
- Rotary Platforms
- Z Axis Linear Transfer



CHAMBERS, UHV VALVES & ACCESSORIES

- · UHV Chambers Manufacturing
- UHV Leak Valves
- UHV Right Angle Valves
- Valve Accessories
- Gaskets
- · Viewports
- Flanges
- Fittings
- Sublimation Pumps
- Feedthroughs
- Ion Gauges
- · Hinged Doors
- · Port Aligners



COMPONENTS

- · CF, KF and ISO Flanges and Fittings
- · Circular Miniature Feedthroughs
- · Co-axial Feedthroughs
- · Power/High Voltage Feedthroughs
- Sub-Miniature D Feedthroughs
- · Thermocouple Feedthroughs
- · Triaxial Feedthroughs
- · Fibre Optics
- · Kapton Wires and Accessories
- Safety Components
- Gauges
- Viewport Accessories
- · Special Custom Built Vacuum Equipment



Diamond Wire Saws



IIII Saw with wire on spool (TWO-WAY-CUT)

Our two-way diamond wire saws work with a spool wire, which is wound onto the wire drum nearly fully automatically. During the separating cut, the diamond wire moves alternately forwards and backwards over the entire length of the wire. This enables a small machine design despite an occupancy of 20 or 30 meters of diamond wire.

- Use of spool wires
- Automatic wire spooling
- Small, compact saw design
- ► Long wire lengths (20 30 m)
- ► Thinnest cut-offs (from 0.08 mm)

DWS.100



The diamond wire saw type DWS.100 is a table saw in horizontal design so that the smallest cut-offs can be observed with the naked eye or by means of an attached microscope.

The maximum workpiece cutting area is 90 x 90 mm and the recommended diamond wire thickness is 0.08 to 0.35 mm.

The continuously adjustable wire speed goes from 0 to 4 m/s.

To ensure a constant cutting pressure, the feed is done by gravity. Workpieces can be cut both wet and dry.

DWS.175 and DWS.250



The diamond wire saw type DWS.175 is a table saw in vertical design.

The maximum workpiece cutting area is 175 x 175 mm and the recommended diamond wire thickness is 0.15 to 0.50 mm.

The DWS.250 type diamond wire saw is currently our largest two-way vertical table saw.

The maximum workpiece cutting area is 250x250 mm and the recommended diamond wire thickness is 0.20 to 0.50 mm.

The continuously adjustable wire speed goes from 0 to 4 m/s. To ensure a constant cutting pressure, the feed is done by gravity. Workpieces can be cut both wet and dry.

Saws for wire loops (ONE-WAY-CUT)

Our one-way diamond wire saws work with endless wire loops. Since these only cut in one direction and the motor is not alternately braked and accelerated again, it is possible to cut at correspondingly higher speeds. Depending on the type of saw, a wire loop 2 to 3 meters in length is used.

- Use of diamond wire loops
- ► Easy and fast application of these loops
- Higher cutting speeds up to 12 m/s
- Clean cut surfaces cut in one direction
- Thin cuts from 0.35 to 0.80 mm

DWS.250E



The diamond wire saw DWS.250E (endless) is a one-way table saw in vertical design.

The maximum workpiece cutting area is 250x250 mm. Diamond wire loops with a length of 2000 mm and thicknesses from 0.35 to 0.60 mm are used.

The continuously adjustable wire speed goes from 4 to 12 m/s.

To ensure a constant cutting pressure, the feed is done by gravity. Workpieces can be cut both wet and dry.

DWS.375E



The diamond wire saw DWS.375E [endless] is currently our largest one-way saw in vertical design.

The maximum workpiece cutting area is T375xH375 mm. Diamond wire loops with a length of 3000 mm and thicknesses from 0.35 to 0.80 mm are used.

The continuously adjustable wire speed goes from 4 to 12 m/s. To ensure a constant cutting pressure, the feed is done by gravity. Workpieces can be cut both wet and dry.



Precision Wire Saws

Precision wire saws available from Princeton Scientific have been developed with an improved cutting technique that utilizes the precision guidance of the width and uniform application of an abrasive slurry. As a result:

- Surface is almost 'lapped' quality
- Cutting does not introduce deformations
- ► Minimal loss of material
- ► Semi-automatic, requires no supervision
- ► Wire diameters from 20µm to 60µm
- No "wandering" of cutting wire into an unintended direction
- Cut samples up to size 80mm x 80mm x 150mm

These precision wire saws are ideal for the precise cutting of:

- Semiconductors
- ► Ferrites
- ► Metals
- Glasses
- Other Hard or Brittle Solids

A variety of precision wire saws are available that can cut samples down to a thickness of 10µm, with smooth cut surfaces where the roughness does not exceed 1µm. With a goniometer mounted to the saw, very precise orientations of crystal surfaces are possible before the cutting process begins.



One Saw, Two Cutting Methods (dry and wet)

The WS-25 wire saw is the first wire saw that can cut with free abrasive method as well as with diamond dotted wire. The WS-25 wire saw is fitted with an adjustable sample support with an electronic vertical axis. The sample is automatically moved up during the cutting process. The wire frame stays at the same vertical position throughout the entire process.

The WS-25 wire saw has been developed to meet two important requirements: 1) cutting should not introduce deformations or defects, and 2) loss of material should be minimized.



These two requirements have been met by the development of an improved cutting technique which utilizes the precision guidance of the wire and uniform application of an abrasive slurry. The WS-25 wire saw is a semi-automatic machine and requires no supervision during its operation. The wire saw can be used for precision cutting of semiconductors, ferrites, metals, and glasses, as well as many other hard or brittle solids. The WS-25 wire saw enables cutting of very thin slices (down to a thickness of 10µm) with smooth cut surfaces (where surface roughness does not exceed 1µm).

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ADVANTAGES

- Semi-automatic, requires no supervision
- Can cut semiconductors, ferrites, metals, glasses and other hard or brittle solids
- Minimizes material losses (>30 µm)
- Slices samples perfectly parallel
- No additional lapping required
- ► Can be used with accessories to extend the saw's application in precision cutting

TECHNICAL DATA

- Sample max dimensions: 80 x 80 mm
- Power Supply: 220-250 V/50 Hz or 110 V/60 Hz
- Tungsten wire diameter: 20-60 μm
- Diamond dotted wire: 100-300 μm
- ▶ Wire oscillation frequency: 150-200/min
- ► Weight: 68 kg
- ▶ Dimensions: 630 x 720 x 250 mm





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www.PrincetonScientific.com

Email: sales@princetonscientific.com · Phone: 609.924.3011 · Fax: 609.924.3018

Princeton Scientific Corp. | P.O. Box 148 | Easton, PA 18044

